

2.5-V TO 3.3-V HIGH-PERFORMANCE CLOCK BUFFER

Check for Samples: [CDCVF2310-EP](#)

FEATURES

- High-Performance 1:10 Clock Driver
- Operates up to 200 MHz at V_{DD} 3.3 V
- Pin-to-Pin Skew < 100 ps at V_{DD} 3.3 V
- V_{DD} Range: 2.3 V to 3.6 V
- Output Enable Glitch Suppression
- Distributes One Clock Input to Two Banks of Five Outputs
- 25- Ω On-Chip Series Damping Resistors
- Packaged in 24-Pin TSSOP

APPLICATIONS

- General-Purpose Applications

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly and Test Site
- One Fabrication Site
- Available in Military (–55°C to 125°C) Temperature Range ⁽¹⁾
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability

(1) Custom temperature ranges available

DESCRIPTION

The CDCVF2310 is a high-performance, low-skew clock buffer that operates up to 200 MHz. Two banks of five outputs each provide low-skew copies of CLK. After power up, the default state of the outputs is low regardless of the state of the control pins. For normal operation, the outputs of bank 1Y[0:4] or 2Y[0:4] can be placed in a low state when the control pins (1G or 2G, respectively) are held low and a negative clock edge is detected on the CLK input. The outputs of bank 1Y[0:4] or 2Y[0:4] can be switched into the buffer mode when the control pins (1G and 2G) are held high and a negative clock edge is detected on the CLK input. The device operates in a 2.5-V and 3.3-V environment. The built-in output enable glitch suppression ensures a synchronized output enable sequence to distribute full period clock signals.

The CDCVF2310 is characterized for operation from –55°C to 125°C.

PW PACKAGE
(TOP VIEW)

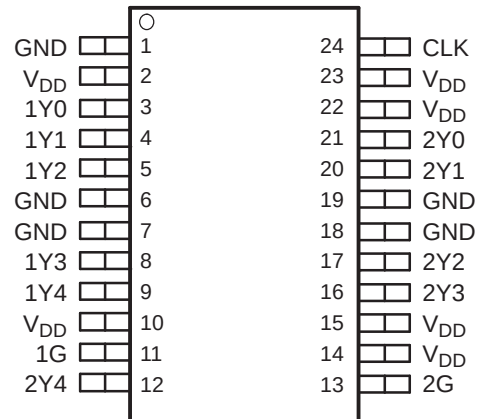


Table 1. ORDERING INFORMATION⁽¹⁾

T _J	PACKAGE	ORDERABLE PART NUMBER	TOP-SIDE MARKING	VID NUMBER
–55°C to 125°C	TSSOP - PW	CDCVF2310MPWREP	CKV2310EP	V62/13603-01XE
		CDCVF2310MPWEP	CKV2310EP	V62/13603-01XE-T

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at [www.ti.com](#).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

FUNCTIONAL BLOCK DIAGRAM

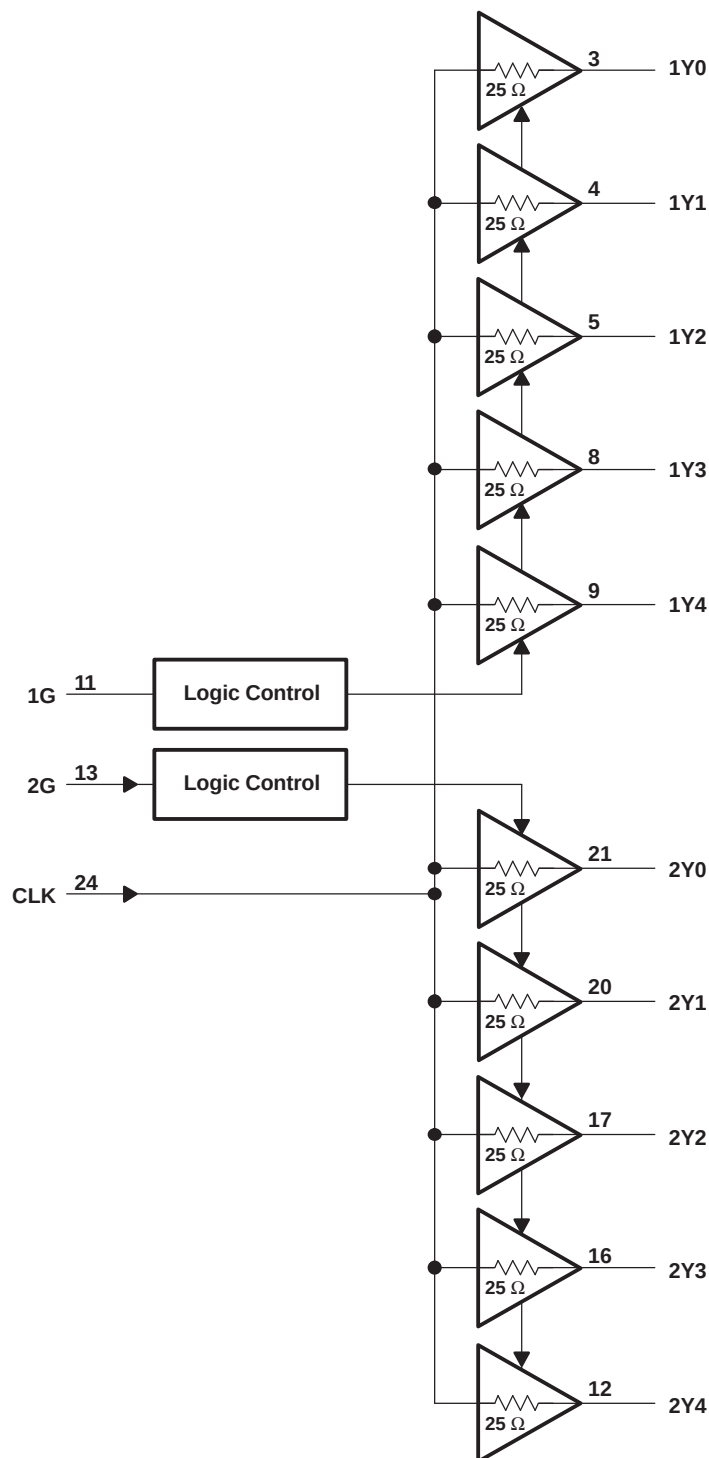


Table 2. FUNCTION TABLE

INPUT			OUTPUT	
1G	2G	CLK	1Y[0:4]	2Y[0:4]
L	L	↓	L	L
H	L	↓	CLK ⁽¹⁾	L
L	H	↓	L	CLK ⁽¹⁾
H	H	↓	CLK ⁽¹⁾	CLK ⁽¹⁾

- (1) After detecting one negative edge on the CLK input, the output follows the input CLK if the control pin is held high.

Terminal Functions

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
1G	11	I	Output enable control for 1Y[0:4] outputs. This output enable is active-high, meaning the 1Y[0:4] clock outputs follow the input clock (CLK) if this pin is logic high.
2G	13	I	Output enable control for 2Y[0:4] outputs. This output enable is active-high, meaning the 2Y[0:4] clock outputs follow the input clock (CLK) if this pin is logic high.
1Y[0:4]	3, 4, 5, 8, 9	O	Buffered output clocks
2Y[0:4]	21, 20, 17, 16, 12	O	Buffered output clocks
CLK	24	I	Input reference frequency
GND	1, 6, 7, 18, 19		Ground
V _{DD}	2, 10, 14, 15, 22, 23		DC power supply, 2.3 V – 3.6 V

ABSOLUTE MAXIMUM RATINGS

over operating junction temperature range (unless otherwise noted) ⁽¹⁾

Supply voltage range, V _{DD}	–0.5 V to 4.6 V
Input voltage range, V _I ⁽²⁾ ⁽³⁾	–0.5 V to V _{DD} + 0.5 V
Output voltage range, V _O ⁽²⁾ ⁽³⁾	–0.5 V to V _{DD} + 0.5 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±50 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±50 mA
Continuous total output current, I _O (V _O = 0 to V _{DD})	±50 mA
Storage temperature range T _{stg}	–65°C to 150°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) This value is limited to 4.6 V maximum.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		CDCVF2310	UNITS
		PW	
		24 PINS	
θ_{JA}	Junction-to-ambient thermal resistance ⁽²⁾	91.7	°C/W
θ_{JCTop}	Junction-to-case (top) thermal resistance ⁽³⁾	31.2	
θ_{JB}	Junction-to-board thermal resistance ⁽⁴⁾	46.4	
ψ_{JT}	Junction-to-top characterization parameter ⁽⁵⁾	1.5	
ψ_{JB}	Junction-to-board characterization parameter ⁽⁶⁾	45.8	
θ_{JCbott}	Junction-to-case (bottom) thermal resistance ⁽⁷⁾	N/A	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a JEDEC-standard, high-K board, as specified in JESD51-7, in an environment described in JESD51-2a.
- (3) The junction-to-case (top) thermal resistance is obtained by simulating a cold plate test on the package top. No specific JEDEC-standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.
- (4) The junction-to-board thermal resistance is obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.
- (5) The junction-to-top characterization parameter, ψ_{JT} , estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA} , using a procedure described in JESD51-2a (sections 6 and 7).
- (6) The junction-to-board characterization parameter, ψ_{JB} , estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA} , using a procedure described in JESD51-2a (sections 6 and 7).
- (7) The junction-to-case (bottom) thermal resistance is obtained by simulating a cold plate test on the exposed (power) pad. No specific JEDEC standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}		2.3	2.5		V
			3.3	3.6	
Low-level input voltage, V_{IL}	$V_{DD} = 3\text{ V to }3.6\text{ V}$			0.8	V
	$V_{DD} = 2.3\text{ V to }2.7\text{ V}$			0.7	
High-level input voltage, V_{IH}	$V_{DD} = 3\text{ V to }3.6\text{ V}$	2			V
	$V_{DD} = 2.3\text{ V to }2.7\text{ V}$	1.7			
Input voltage, V_i		0		V_{DD}	V
High-level output current, I_{OH}	$V_{DD} = 3\text{ V to }3.6\text{ V}$			12	mA
	$V_{DD} = 2.3\text{ V to }2.7\text{ V}$			6	
Low-level output current, I_{OL}	$V_{DD} = 3\text{ V to }3.6\text{ V}$			12	mA
	$V_{DD} = 2.3\text{ V to }2.7\text{ V}$			6	
Operating junction temperature, T_J		-55		125	°C

- (1) Unused inputs must be held high or low to prevent them from floating.

ELECTRICAL CHARACTERISTICS

over recommended operating junction temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK}	Input voltage	V _{DD} = 3 V,	I _I = −18 mA			−1.2	V
I _I	Input current	V _I = 0 V or V _{DD}				±5	μA
I _{DD} ⁽²⁾	Static device current	CLK = 0 V or V _{DD} ,	I _O = 0 mA			100	μA
C _I	Input capacitance	V _{DD} = 2.3 V to 3.6 V,	V _I = 0 V or V _{DD}		2.5		pF
C _O	Output capacitance	V _{DD} = 2.3 V to 3.6 V,	V _I = 0 V or V _{DD}		2.8		pF
V_{DD} = 3.3 V ±0.3 V							
V _{OH}	High-level output voltage	V _{DD} = min to max,	I _{OH} = −100 μA	V _{DD} − 0.2			V
		V _{DD} = 3 V	I _{OH} = −12 mA	2.1			
			I _{OH} = −6 mA	2.4			
V _{OL}	Low-level output voltage	V _{DD} = min to max,	I _{OL} = −100 μA	0.2			V
		V _{DD} = 3 V	I _{OL} = 12 mA	0.8			
			I _{OL} = 6 mA	0.55			
I _{OH}	High-level output current	V _{DD} = 3 V,	V _O = 1 V	−28			mA
		V _{DD} = 3.3 V,	V _O = 1.65 V	−36			
		V _{DD} = 3.6 V,	V _O = 3.135 V	−14			
I _{OL}	Low-level output current	V _{DD} = 3 V,	V _O = 1.95 V	28			mA
		V _{DD} = 3.3 V,	V _O = 1.65 V	36			
		V _{DD} = 3.6 V,	V _O = 0.4 V	14			
V_{DD} = 2.5 V ±0.2 V							
V _{OH}	High-level output voltage	V _{DD} = min to max,	I _{OH} = −100 μA	V _{DD} − 0.2			V
		V _{DD} = 2.3 V	I _{OH} = −6 mA	1.8			
V _{OL}	Low-level output voltage	V _{DD} = min to max,	I _{OL} = 100 μA	0.2			V
		V _{DD} = 2.3 V	I _{OL} = 6 mA	0.55			
I _{OH}	High-level output current	V _{DD} = 2.3 V,	V _O = 1 V	−15			mA
		V _{DD} = 2.5 V,	V _O = 1.25 V	−25			
		V _{DD} = 2.7 V,	V _O = 2.375 V	−10			
I _{OL}	Low-level output current	V _{DD} = 2.3 V,	V _O = 1.2 V	15			mA
		V _{DD} = 2.5 V,	V _O = 1.25 V	25			
		V _{DD} = 2.7 V,	V _O = 0.3 V	10			

(1) All typical values are at respective nominal V_{DD}.

(2) For I_{CC} over frequency, see [Figure 6](#).

TIMING REQUIREMENTS

over recommended ranges of supply voltage and operating junction temperature

		MIN	NOM	MAX	UNIT
f_{clk}	Clock frequency	$V_{\text{DD}} = 3 \text{ V to } 3.6 \text{ V}$		0	200
		$V_{\text{DD}} = 2.3 \text{ V to } 2.7 \text{ V}$		0	170
					MHz

JITTER CHARACTERISTICS

Characterized using CDCVF2310 Performance EVM when $V_{\text{DD}}=3.3 \text{ V}$. Outputs not under test are terminated to 50 Ω .

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{jitter}	Additive phase jitter from input to output 1Y0	12 kHz to 5 MHz, $f_{\text{out}} = 30.72 \text{ MHz}$		52	fs rms
		12 kHz to 20 MHz, $f_{\text{out}} = 125 \text{ MHz}$		45	

SWITCHING CHARACTERISTICS

over recommended operating junction temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{\text{DD}} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (see Figure 2)					
t_{PLH}	CLK to Yn $f = 0 \text{ MHz to } 200 \text{ MHz}$ For circuit load, see Figure 2 .	1.3		3.3	ns
t_{PHL}					
$t_{\text{sk(o)}}$	Output skew (Ym to Yn) ⁽¹⁾ (see Figure 4)			100	ps
$t_{\text{sk(p)}}$	Pulse skew (see Figure 5)			570	ps
$t_{\text{sk(pp)}}$	Part-to-part skew			500	ps
t_{r}	Rise time (see Figure 3) $V_{\text{O}} = 0.4 \text{ V to } 2 \text{ V}$	0.7		2.2	V/ns
t_{f}	Fall time (see Figure 3) $V_{\text{O}} = 2 \text{ V to } 0.4 \text{ V}$	0.7		2.2	V/ns
$t_{\text{su(en)}}$	Enable setup time, G_high before CLK $\downarrow$	0.1			ns
$t_{\text{su(dis)}}$	Disable setup time, G_low before CLK $\downarrow$	0.1			ns
$t_{\text{h(en)}}$	Enable hold time, G_high after CLK $\downarrow$	0.4			ns
$t_{\text{h(dis)}}$	Disable hold time, G_low after CLK $\downarrow$	0.4			ns
$V_{\text{DD}} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (see Figure 2)					
t_{PLH}	CLK to Yn $f = 0 \text{ MHz to } 170 \text{ MHz}$ For circuit load, see Figure 2 .	1.5		4	ns
t_{PHL}					
$t_{\text{sk(o)}}$	Output skew (Ym to Yn) ⁽¹⁾ (see Figure 4)			170	ps
$t_{\text{sk(p)}}$	Pulse skew (see Figure 5)			680	ps
$t_{\text{sk(pp)}}$	Part-to-part skew			600	ps
t_{r}	Rise time (see Figure 3) $V_{\text{O}} = 0.4 \text{ V to } 1.7 \text{ V}$	0.5		1.4	V/ns
t_{f}	Fall time (see Figure 3) $V_{\text{O}} = 1.7 \text{ V to } 0.4 \text{ V}$	0.5		1.4	V/ns
$t_{\text{su(en)}}$	Enable setup time, G_high before CLK $\downarrow$	0.1			ns
$t_{\text{su(dis)}}$	Disable setup time, G_low before CLK $\downarrow$	0.1			ns
$t_{\text{h(en)}}$	Enable hold time, G_high after CLK $\downarrow$	0.4			ns
$t_{\text{h(dis)}}$	Disable hold time, G_low after CLK $\downarrow$	0.4			ns

(1) The $t_{\text{sk(o)}}$ specification is only valid for equal loading of all outputs.

DETAILED DESCRIPTION

Output Enable Glitch Suppression Circuit

The purpose of the glitch suppression circuitry is to ensure the output enable sequence is synchronized with the clock input such that the output buffer is enabled or disabled on the next full period of the input clock (negative edge triggered by the input clock) (see [Figure 1](#)).

The G input must fulfill the timing requirements (t_{su} , t_h) according to the *Switching Characteristics* table for predictable operation.

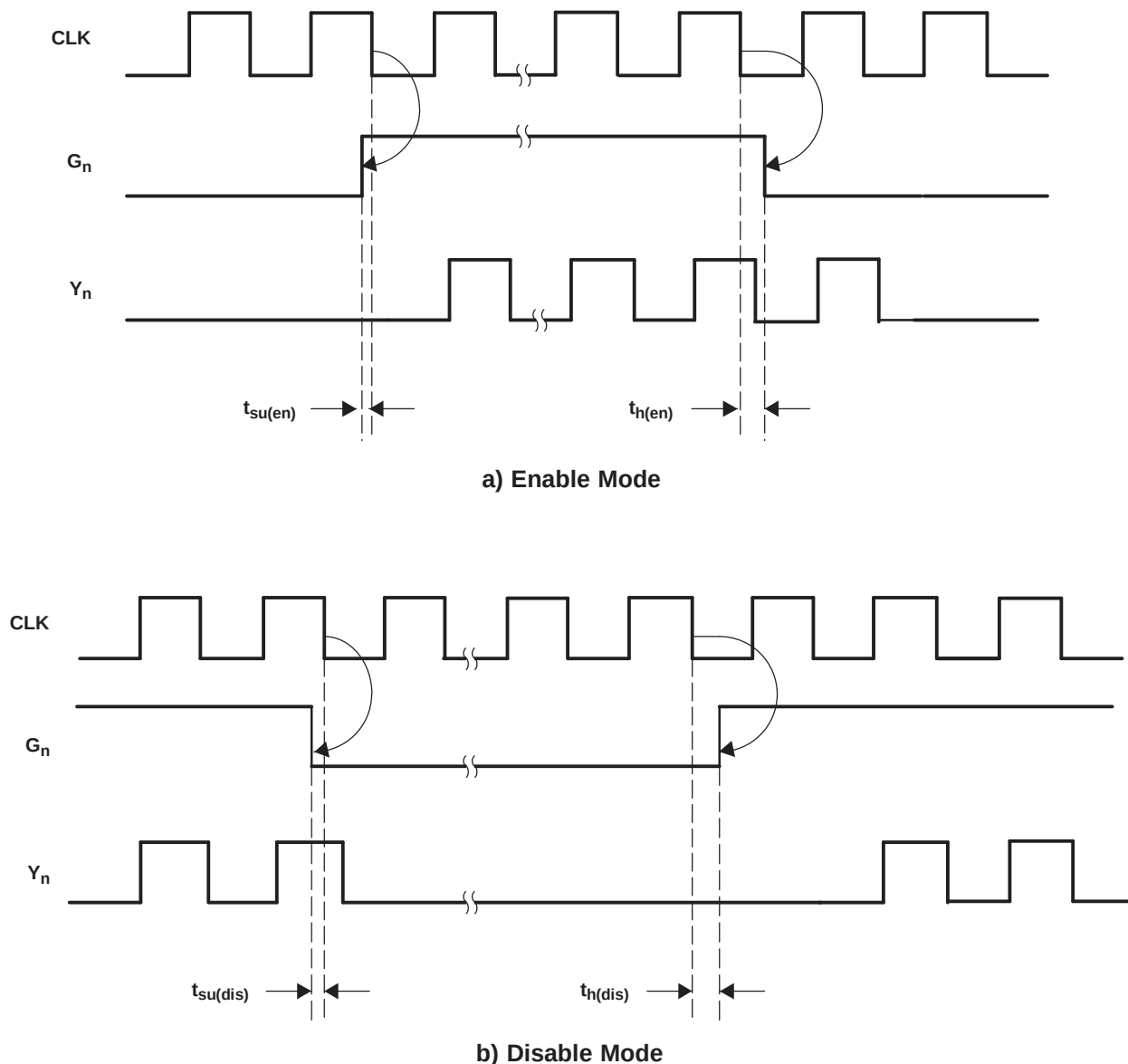
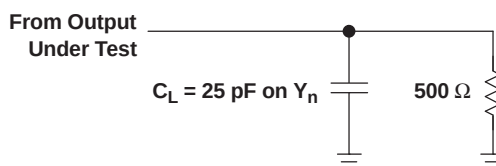


Figure 1. Enable and Disable Mode Relative to CLK↓

PARAMETER MEASUREMENT INFORMATION



- A. C_L includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 200$ MHz, $Z_O = 50 \Omega$, $t_r < 1.2$ ns, $t_f < 1.2$ ns.

Figure 2. Test Load Circuit

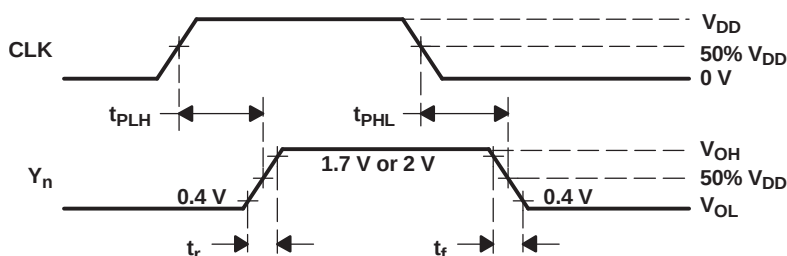


Figure 3. Voltage Waveforms Propagation Delay Times

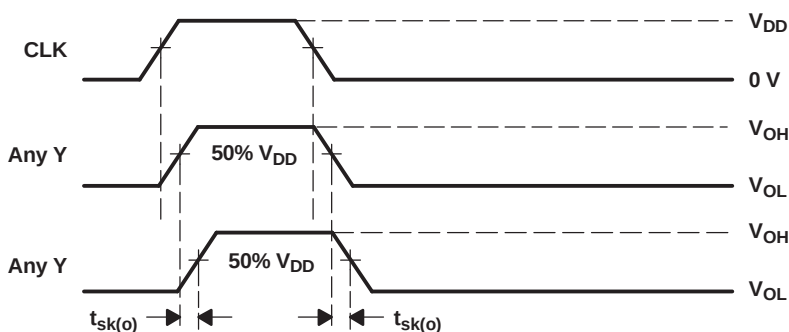
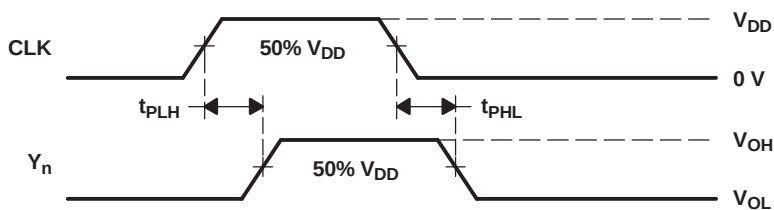


Figure 4. Output Skew



NOTE: $t_{sk(p)} = |t_{PLH} - t_{PHL}|$

Figure 5. Pulse Skew

PARAMETER MEASUREMENT INFORMATION (continued)

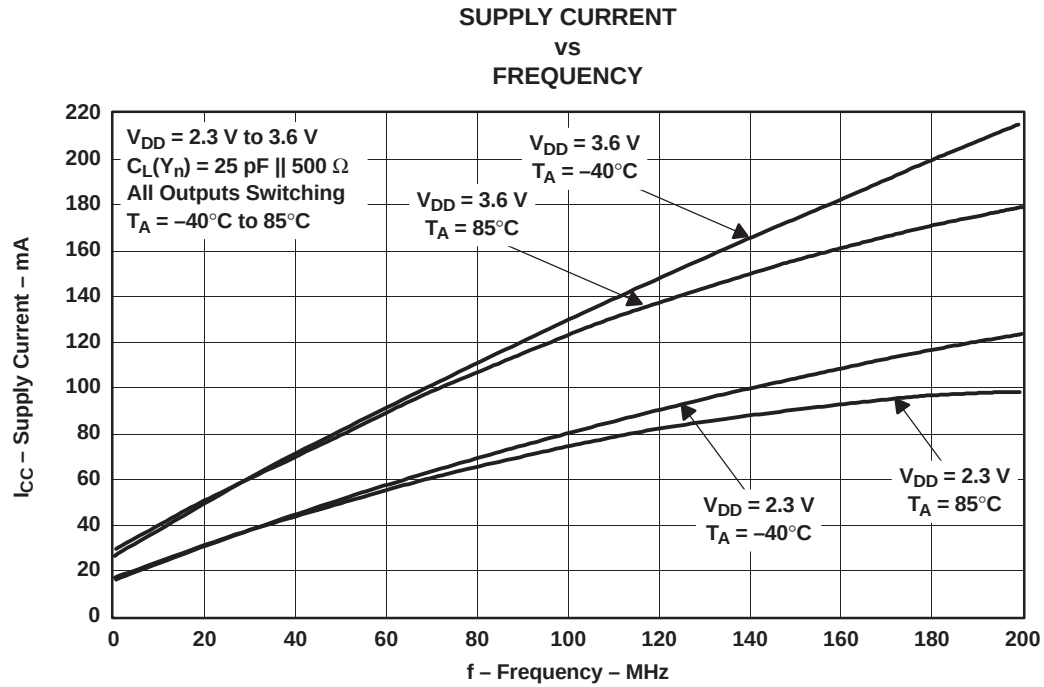


Figure 6.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CDCVF2310MPWEP	Active	Production	TSSOP (PW) 24	60 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CKV2310EP
CDCVF2310MPWREP	Active	Production	TSSOP (PW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CKV2310EP

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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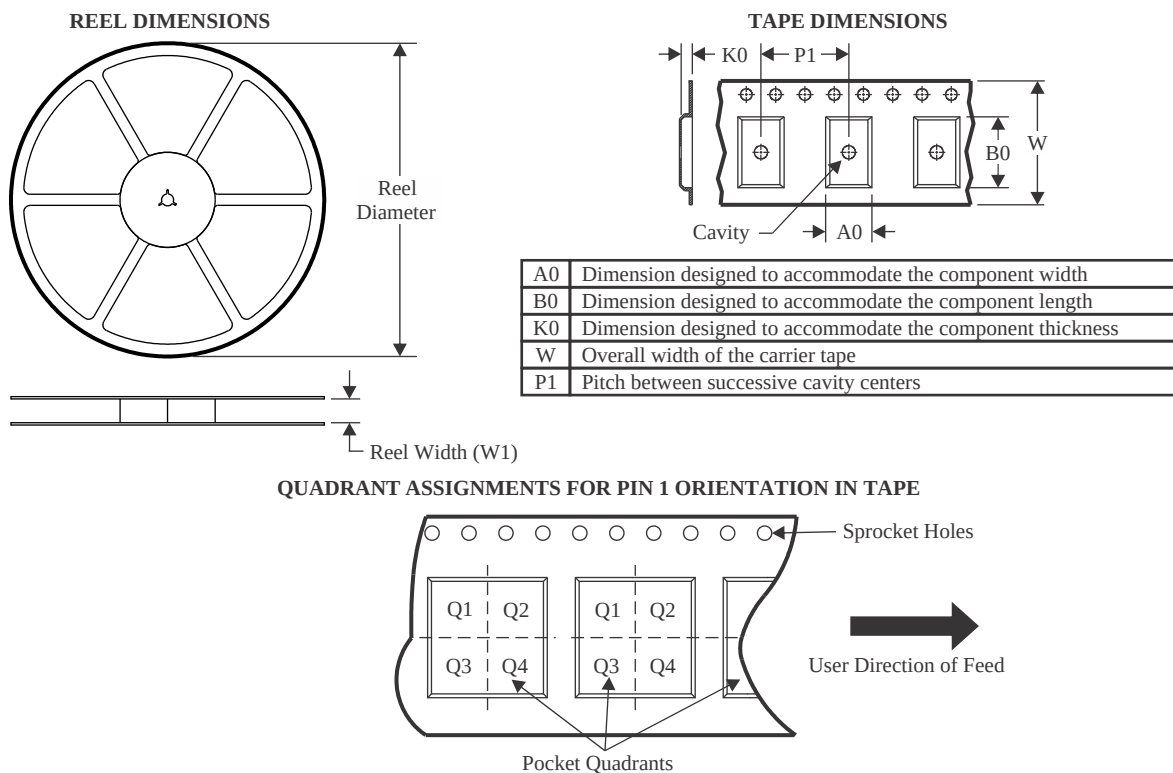
OTHER QUALIFIED VERSIONS OF CDCVF2310-EP :

- Catalog : [CDCVF2310](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

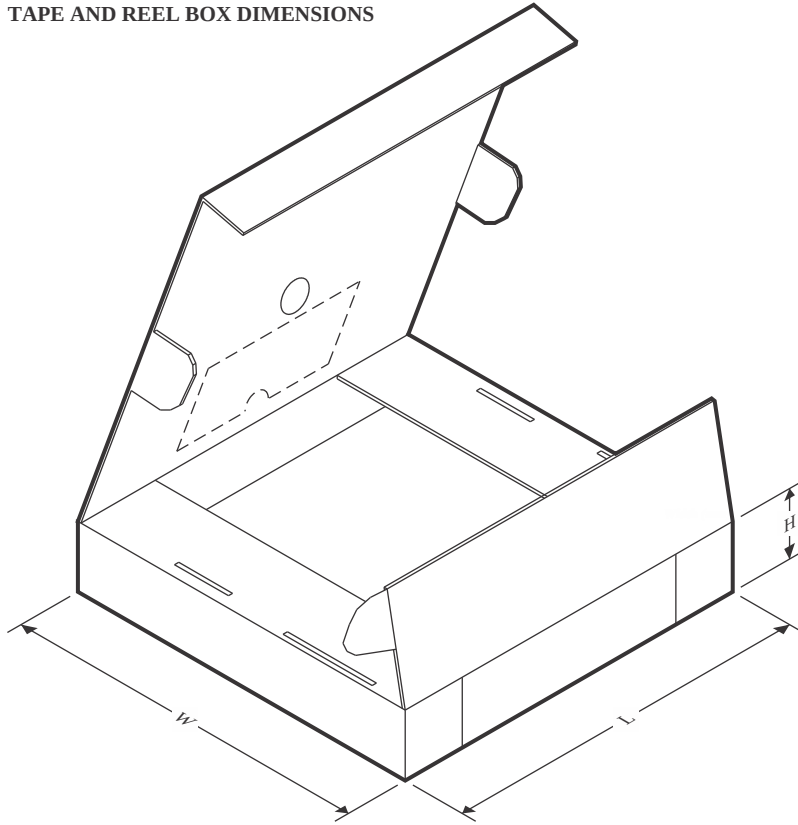
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCVF2310MPWREP	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

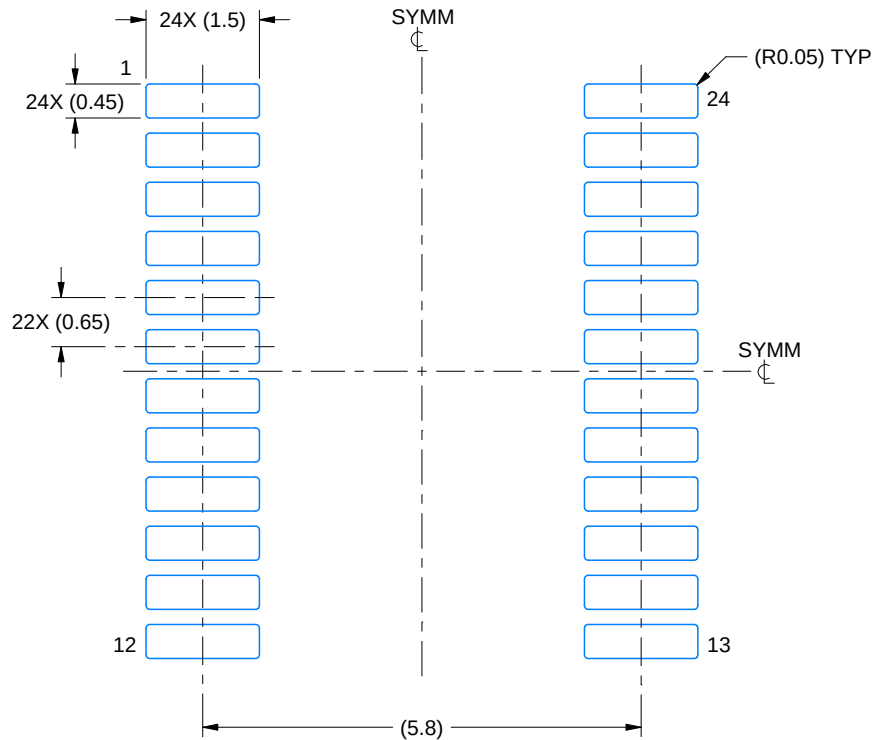
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCVF2310MPWREP	TSSOP	PW	24	2000	356.0	356.0	35.0

EXAMPLE BOARD LAYOUT

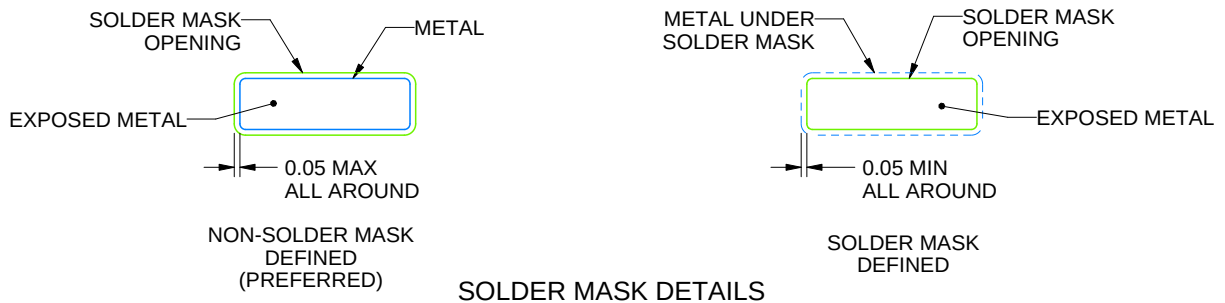
PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

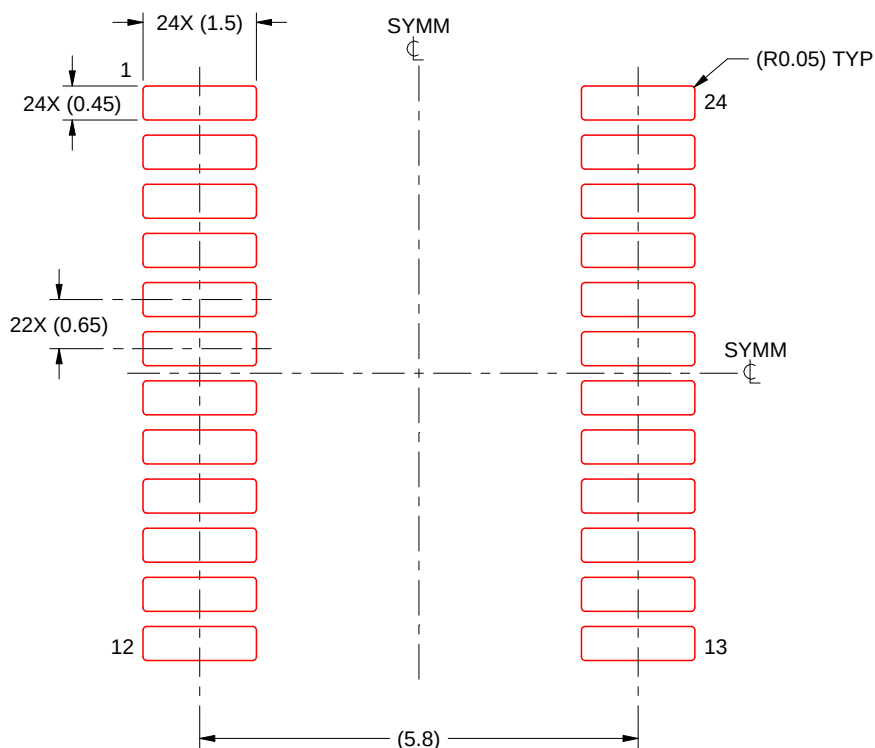
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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